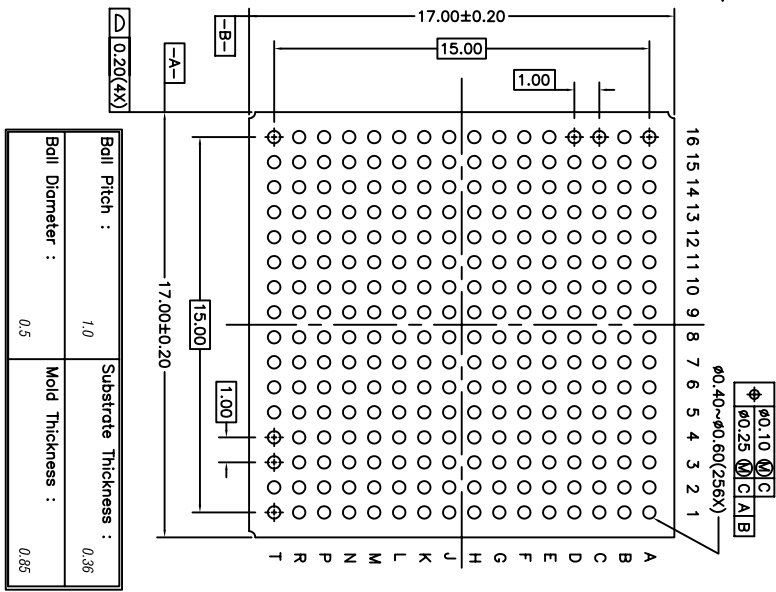
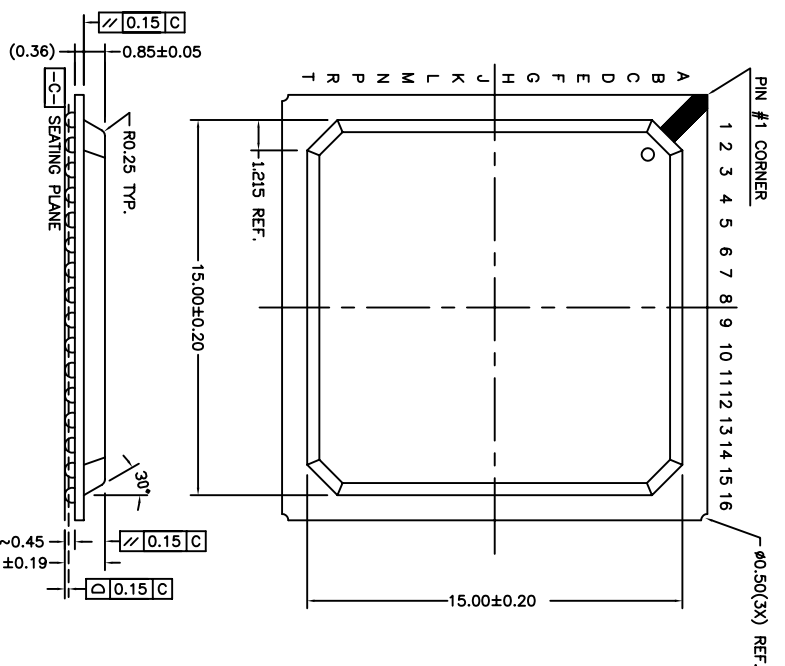


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	07/08/09	P.PAIK
01	COMBINE POD & LAND PATTERN	06/05/13	KS



Ball Pitch :	1.0	Substrate Thickness :	0.36
Ball Diameter :	0.5	Mold Thickness :	0.85

TOLERANCES UNLESS SPECIFIED
DECIMAL ANGULAR ±1°
XXX±.05
XXXX±.030

APPROVALS DATE
DRAWN *dadg* 7/7/09
CHECKED

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6024 SILVER CREEK VALLEY ROAD, SAN JOSE, CA 95138
PHONE: (408) 284-8200
FAX: (408) 284-3572

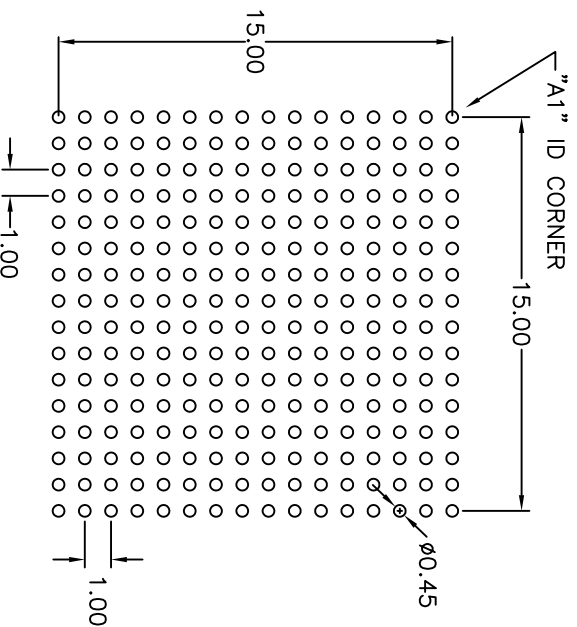
TITLE AM/AMG 256 PACKAGE OUTLINE
17 x 17 mm BODY
1.00 mm PITCH PBGA

SIZE C DRAWING No. PSC-4263

DO NOT SCALE DRAWING

SHEET 1 OF 2


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	07/08/09	P.PAIK
01	COMBINE POD & LAND PATTERN	06/05/13	KS



RECOMMENDED LAND PATTERN DIMENSION

NOTE:

- 1) ALL dimensions are in mm, Angles in degrees.
- 2) Top down view, as view on PCB.
- 3) NSMD Land Pattern Assumed
- 4) Land Pattern Recommendation as per IPC-7351B generic requirement for surface mount design and Land Pattern.

TOLERANCES UNLESS SPECIFIED	ANGULAR	±1°	 6024 SILVER CREEK VALLEY ROAD, SAN JOSE, CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-3572 www.IDT.com
DECIMAL			
XX± .1			TITLE AM/AMG 256 PACKAGE OUTLINE 17 x 17 mm BODY 1.00 mm PITCH PBGA
XXX± .05			
XXXX± .030	DATE	7/7/09	SIZE C
APPROVALS	DRAWN	02d/c	DRAWING No. PSC-4263
CHECKED			REV 01
			DO NOT SCALE DRAWING
			SHEET 2 OF 2